

AMS-UltraClean-RMS-REV-02

Date: 10/2022

Semiconductor Quality- TUBES seamless below 1" OD-

1. SCOPE

This technical specification has the objective to define the delivery conditions for Stainless steel according to the grade which is defined in point 5. The purpose of this specification is to define the metallurgical cleanliness requirements and material composition of 316L stainless steel Billets, Rounds Rectangular and square bars required for use in Semiconductor Industry. The finished goods are primarily used as sealing parts. Other applications consists of thin wall hollow stressed parts. This material is intended for subsequent fabrication processes such as forging fabrication and then after machining, mechanical polishing, TIG/AOW operation and electro polish.

2. Material Designation

X2CrNiMo18-14-3 AISI 316L 1.4435 modified

3. Manufacturing

The stainless steel shall usually be manufactured with primary melting process of Electric Arc Furnace(EAF) or Vacuum Induction Melting (VIM), with refining process of Argon Oxygen Decarburization(AOD) or Vacuum Oxygen Decarburization (VOD), followed by secondary melting process of Electro-slag Remelting (ESR) or Vacuum Arc Remelting (VAR) when needed.

4. General Requirements

Seamless Tubes from OD 5.00mm – OD 25.40mm

OD tolerance +0.00/-0.20mm

Wall thickness 1.00mm up to 2.54mm

Tolerance WT +/- 0.10mm

Max length 3,000mm (-0/+200)

Straightness 0.10 / metre

SEMI-F20-UHP-latest version,

5. Chemical composition (weight %)

		C	Si	Mn	P	S	Cr	Mo	Ni	Cu	Nb	AI	Ca	Ti
M	l in	0.015	0.400	-	-	0.005	16.500	2.300	12.000	-	-	-	-	-
M	[ax	0.030	0.600	0.500	0.025	0.010	18.000	-	-	0.300	0.050	0.010	0.020	0.020

	Se	Co	N
Min	-	-	-
Max	0.020	0.100	0.060



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6. Mechanical Properties

SEMI F20-0706E 09-2017 UHP EN 10088-3 12-2014, ASTM 269

	Tensile Strength	Yield Strength (0.2% offset)	Elong. in 2" or 4D	Red. Area	Hardness, (Mid radius)	Grain Size
OD 6mm – 25.40mm						
WT 0.50mm - 1.50mm	650.00	500.00	-	-	195.00	6 and above
UNITS	MPa min.	MPa min.	% min	% min	HB min.	-

7. Cleanliness

The inclusion content of the material shall be determined from representative samples of the material heat in accordance with ASTM E 45 Method A, but with ratings based on Plate III. Maximum allowable JK ratings at the billet stage are shown below.

TYPE	THIN	HEAVY		
A	1.00	0.50		
В	1.00	0.50		
С	1.00	0.50		
D	1.00	0.50		

8. Metallurgy

Grain size per ASTM E112 shall be 6 or finer.

Intergranular corrosion test according to ASTM A 262 practice E.

Macro etch test to be conducted for one sample per heat / size , in accordance with ASTM A604/604 M.

9. Surface Condition

Smooth, bright, no corrosion points,

no rust,

no cracks.

no scores no surface defects,

100% eddy current according DIN EN 10277 CLASS 3,



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10. Internal Defect(s)

State-of-the-art measures are to be taken in order to avoid the occurrence of macroscopic internal defects.

Delivery condition: no internal defects,

no cracks, no blow holes,

no non-metallic inclusions.

100% ultrasonic test on bars according to DIN EN 10308 quality class 3.

11. Delivery condition,

Printed on bars or stamped on bar end (one side only), heat# and size (applies to bars above 1") Bars are packed in wooden crates suitable for export,

12. Material Test Reports,

Test certificate acc. to standards specified in the order complying to DIN EN 10204/3.1

Heat number,

Chemical composition,

Grade,

All further treatment,

Quantity delivered,

Inclusions test result,

Material free of Mercury contamination statement & Material free of Radioactivity statement

ROHS and REACH compliance,

Results, third party test(s),